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可靠性实验

外形尺寸

包装

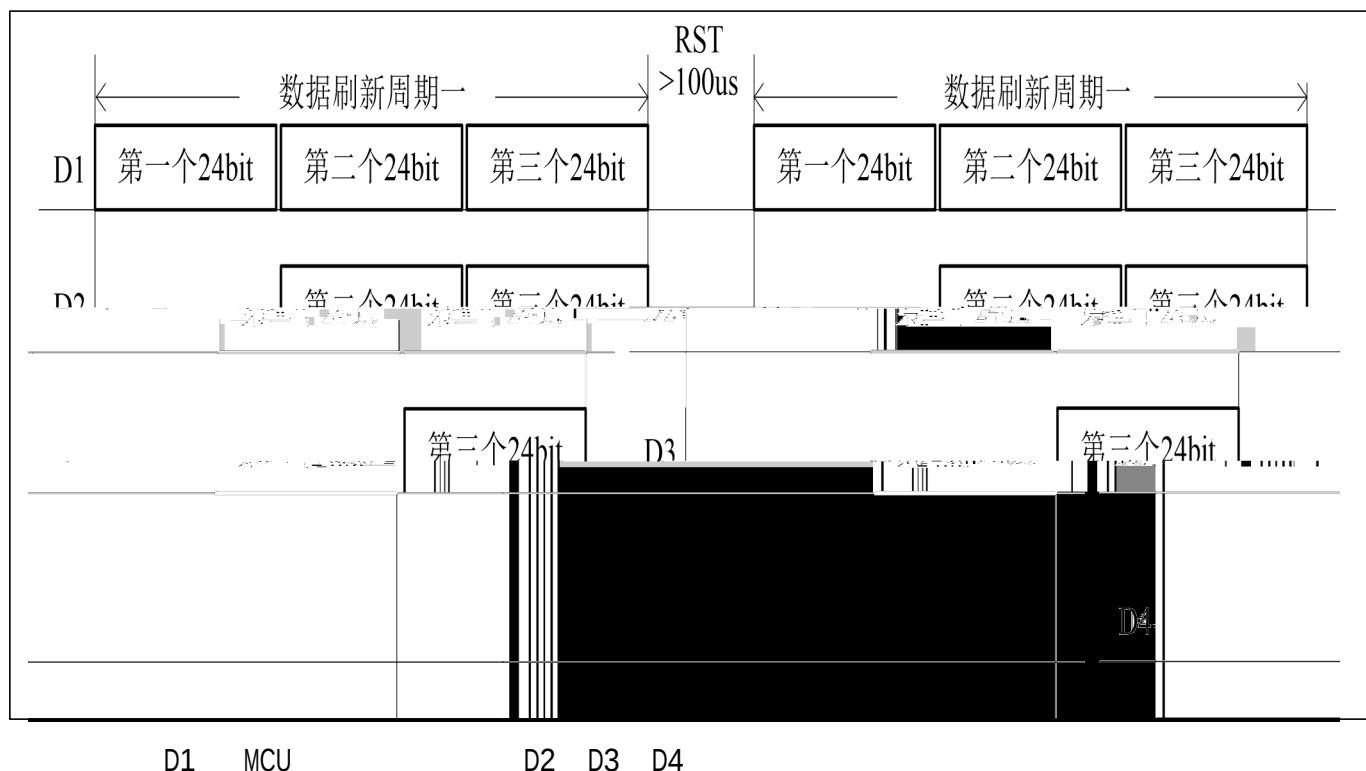
焊接指导

注意事项





Date transmission mode



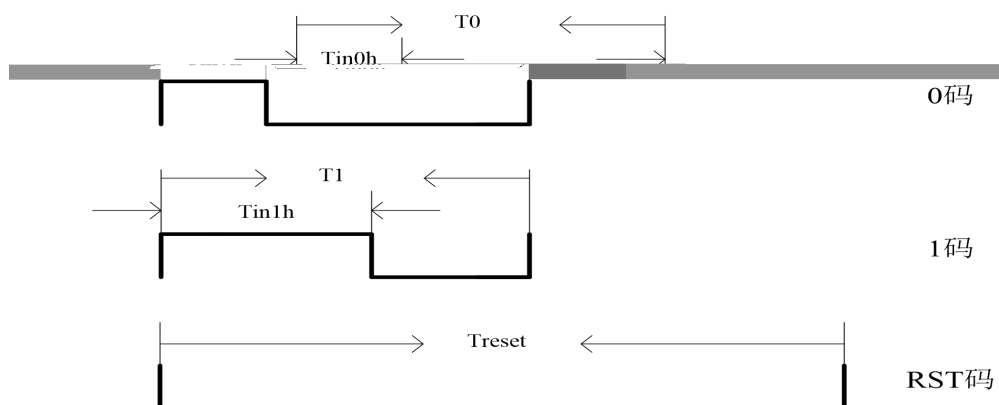
Note: D1 refers to the data sent by MCU, and D2, D3 and D4 refer to the data automatically shaped and forwarded by cascade circuit

24bit 24bit data structure



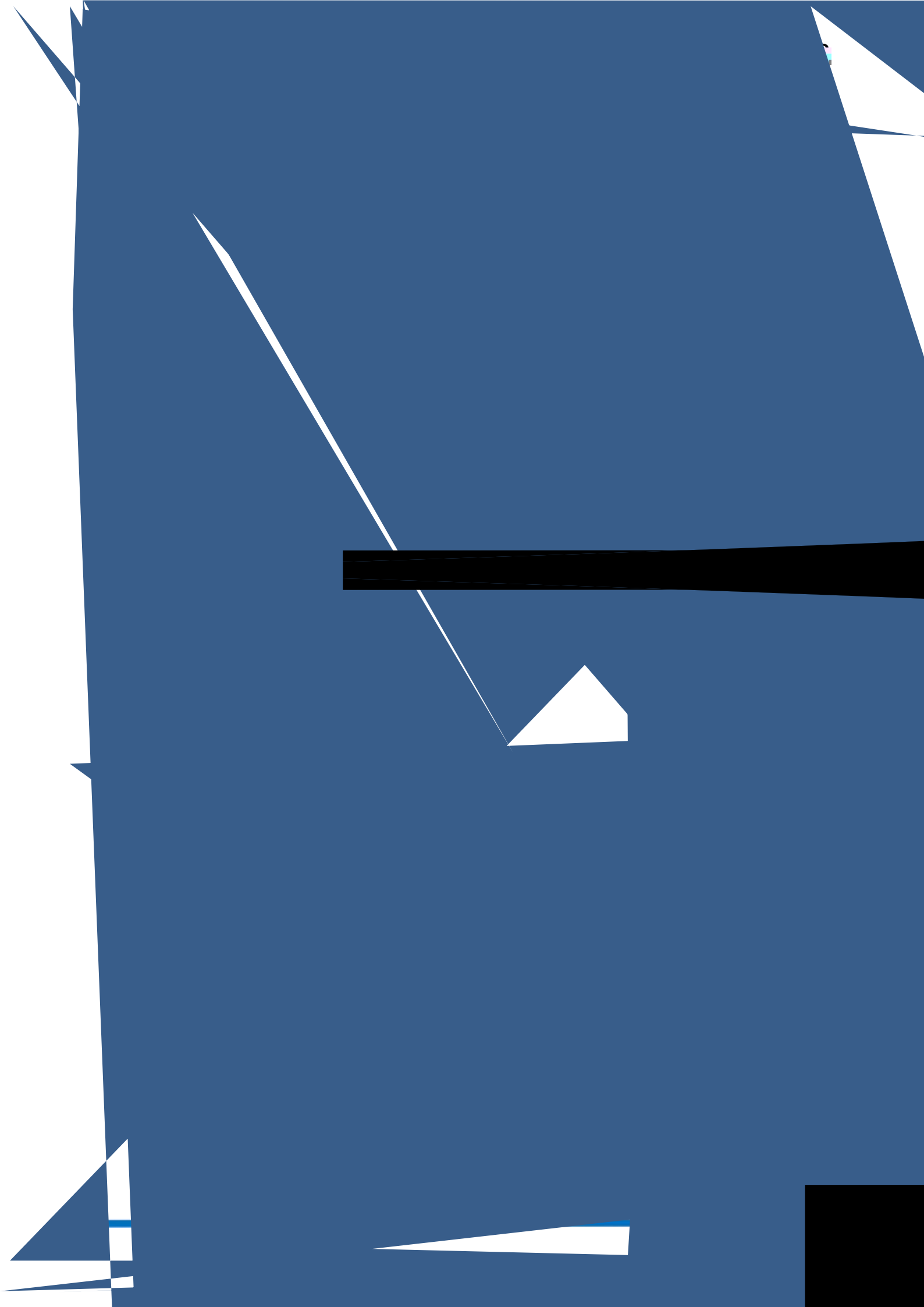
Note: high order first send, send data in the order of GrB

:Time sequence waveform:







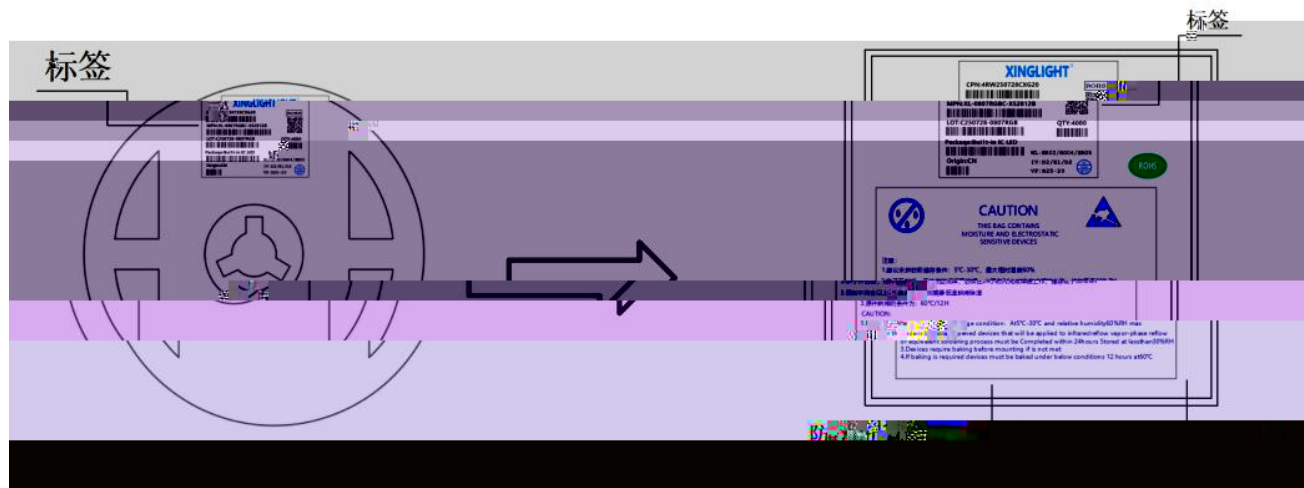




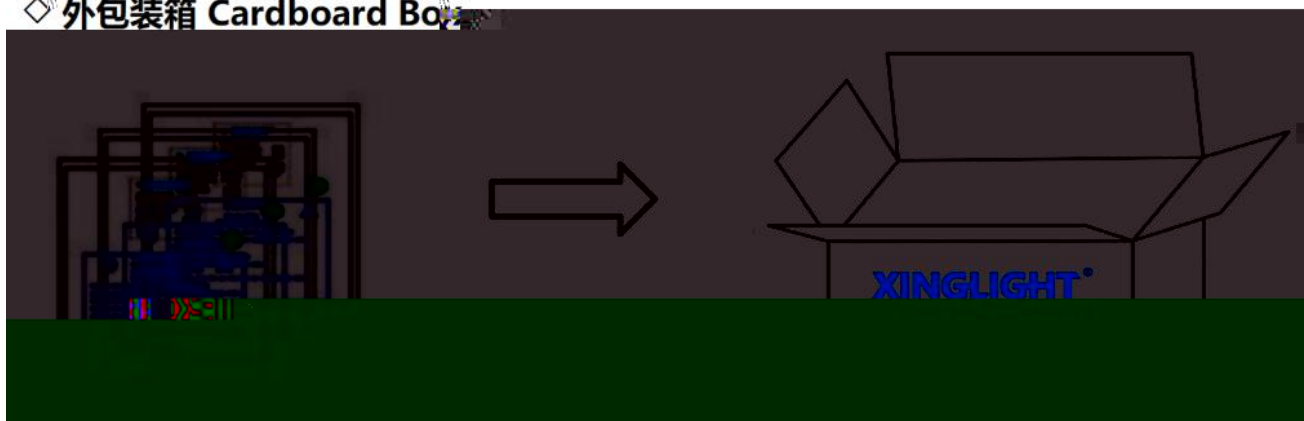
包装 (2)

Packaging (2)

◇ 防潮防静电包装 Moisture Proof and Antti-Electrostatic Foil Bag



◇ 外包装箱 Cardboard Box



◇ 标签说明 Label Explanation



焊接指导 (1)

Guideline for Solder

使用烙铁手工焊接

严禁手入灯腔内





